

Product Summary

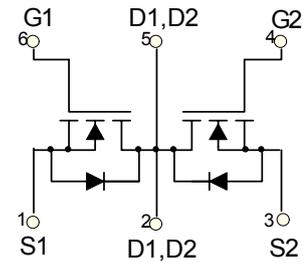
| Part # | V_{DS} | $R_{DS(on).typ}$ (@ $V_{GS}=4.5V$) | $R_{DS(on).typ}$ (@ $V_{GS}=2.5V$) | I_D |
|---------|----------|--|--|-------|
| EFM8205 | 20V | 20m Ω | 26m Ω | 6A |

Description

- The EFM8205 is the high cell density trenched
- N-ch MOSFETs which provide excellent
- RDSON and gate charge for most of the
- synchronous buck converter applications.
- The EFM8205 meet the RoHS and Green
- Product requirement, 100 % EAS guaranteed
- with full function reliability approved.

Application

- Super Low Gate Charge 100% EAS Guaranteed
- Green Device Available Excellent CdV/dt effect decline
- Advanced high cell density Trench technology



N-Channel MOSFET



SOT-23-6L

Ordering Information:

| | |
|---------------------------|-----------|
| Part NO. | EFM8205 |
| Marking | 8205A |
| Packing Information | REEL TAPE |
| Basic ordering unit (pcs) | 3000 |

Absolute Maximum Ratings ($T_C=25^\circ C$)

| Parameter | Symbol | Limit | Unit |
|--|----------------|------------|------------|
| Drain-Source Voltage | V_{DS} | 20 | V |
| Gate-Source Voltage | V_{GS} | ± 12 | V |
| Drain Current-Continuous | I_D | 6 | A |
| Drain Current-Pulsed ^(Note 1) | I_{DM} | 20 | A |
| Maximum Power Dissipation | P_D | 1.2 | W |
| Operating Junction and Storage Temperature Range | T_J, T_{STG} | -55 To 150 | $^\circ C$ |

Thermal Characteristic

| | | | |
|---|-----------------|-----|--------------|
| Thermal Resistance, Junction-to-Ambient ^(Note 2) | $R_{\theta JA}$ | 100 | $^\circ C/W$ |
|---|-----------------|-----|--------------|

• Static Electrical Characteristics @ T_J = 25°C (unless otherwise stated)

| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|------------------------------------|---------------------|--|-----|------|------|------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | V _{GS} =0V I _D =250uA | 20 | -- | -- | V |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} =20V V _{GS} =0V | -- | -- | 1 | μA |
| Gate-Body Leakage Current | I _{GSS} | V _{GS} =±12V V _{DS} =0V | -- | -- | ±100 | nA |
| On Characteristics (Note 3) | | | | | | |
| Gate Threshold Voltage | V _{GS(th)} | V _{DS} =V _{GS} I _D =250uA | 0.5 | 0.7 | 1.2 | V |
| Drain-Source On-State Resistance | R _{DS(on)} | V _{GS} =4.5V I _D =6A | -- | 20 | 27 | mΩ |
| | | V _{GS} =2.5V I _D =5A | -- | 26 | 32 | mΩ |
| Forward Transconductance | g _{FS} | V _{DS} =5V I _D =6A | -- | 17.7 | -- | S |

| | | | | | | |
|---|---------------------|---|----|------|-----|----|
| Dynamic Characteristics (Note4) | | | | | | |
| Input Capacitance | C _{iss} | V _{DS} =10V V _{GS} =0V F=1.0MHz | -- | 802 | -- | PF |
| Output Capacitance | C _{oss} | | -- | 153 | -- | PF |
| Reverse Transfer Capacitance | C _{rss} | | -- | 122 | -- | PF |
| Switching Characteristics (Note 4) | | | | | | |
| Turn-on Delay Time | t _{d(on)} | V _{DD} =10V I _D =1A V _{GS} =4.5V R _G =10Ω, | -- | 18 | -- | nS |
| Turn-on Rise Time | t _r | | -- | 5 | -- | nS |
| Turn-Off Delay Time | t _{d(off)} | | -- | 43.8 | -- | nS |
| Turn-Off Fall Time | t _f | | -- | 20 | -- | nS |
| Total Gate Charge | Q _g | V _{DS} =10V I _D =4A V _{GS} =4.5V | -- | 10.5 | -- | nC |
| Gate-Source Charge | Q _{gs} | | -- | 2 | -- | nC |
| Gate-Drain Charge | Q _{gd} | | -- | 2.5 | -- | nC |
| Drain-Source Diode Characteristics | | | | | | |
| Diode Forward Voltage (Note 3) | V _{SD} | V _{GS} =0V I _S =1.7A | -- | 0.75 | 1.2 | V |
| Diode Forward Current (Note 2) | I _S | | -- | -- | 1.7 | A |

Notes:

a. Surface Mounted on FR4 Board ,T<10 sec ;

• Typical Characteristics

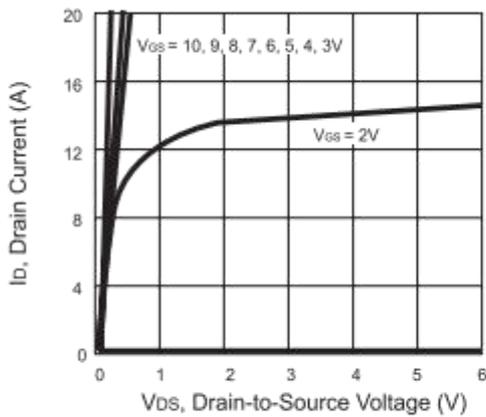


Figure 1. Output Characteristics

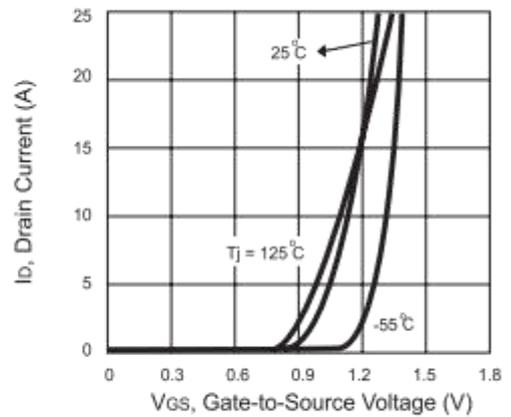


Figure 2. Transfer Characteristics

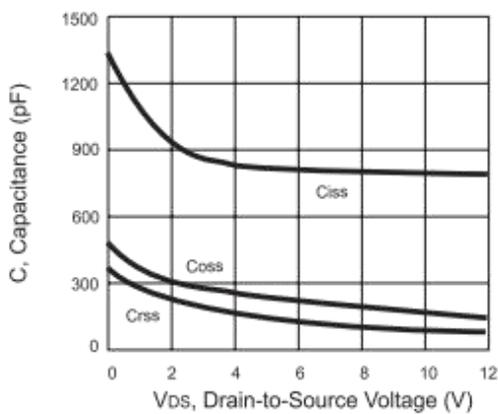


Figure 3. Capacitance

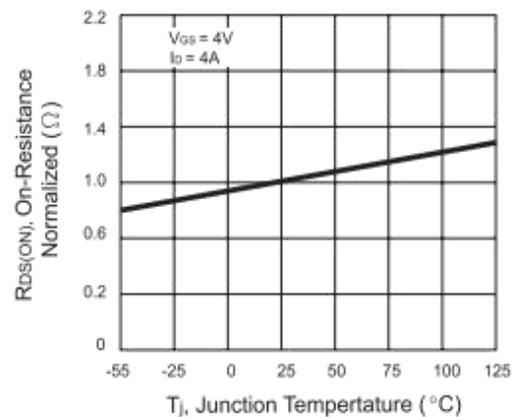


Figure 4. On-Resistance Variation with Temperature

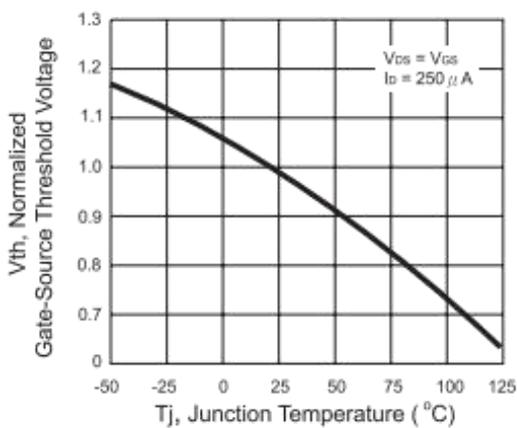


Figure 5. Gate Threshold Variation with Temperature

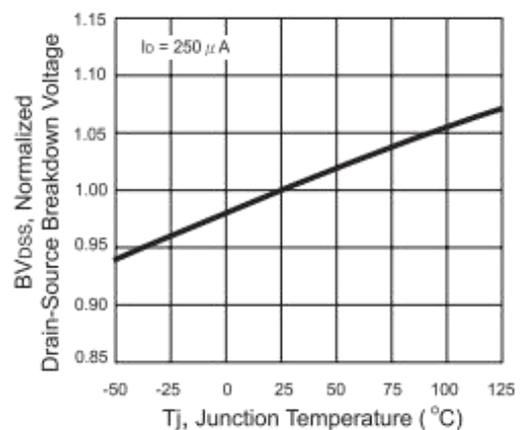


Figure 6. Breakdown Voltage Variation with Temperature

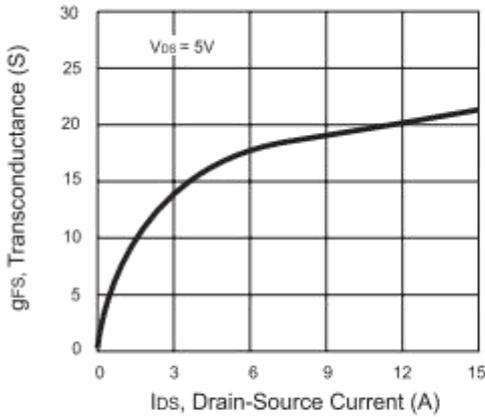


Figure 7. Transconductance Variation with Drain Current

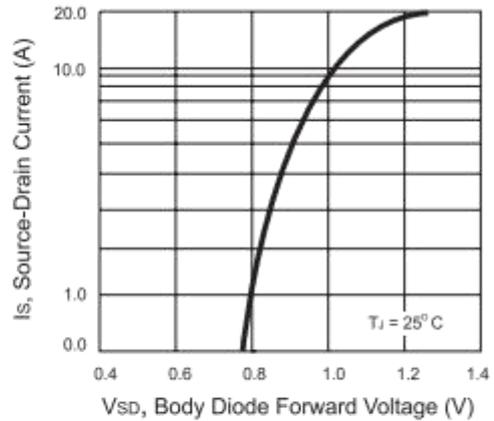


Figure 8. Body Diode Forward Voltage Variation with Source Current

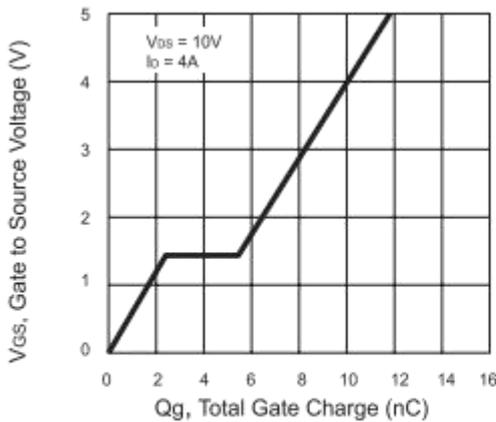


Figure 9. Gate Charge

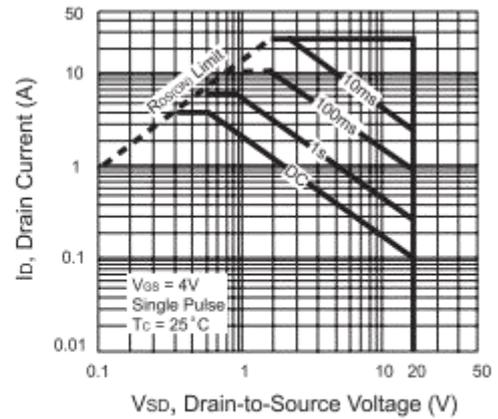


Figure 10. Maximum Safe Operating Area

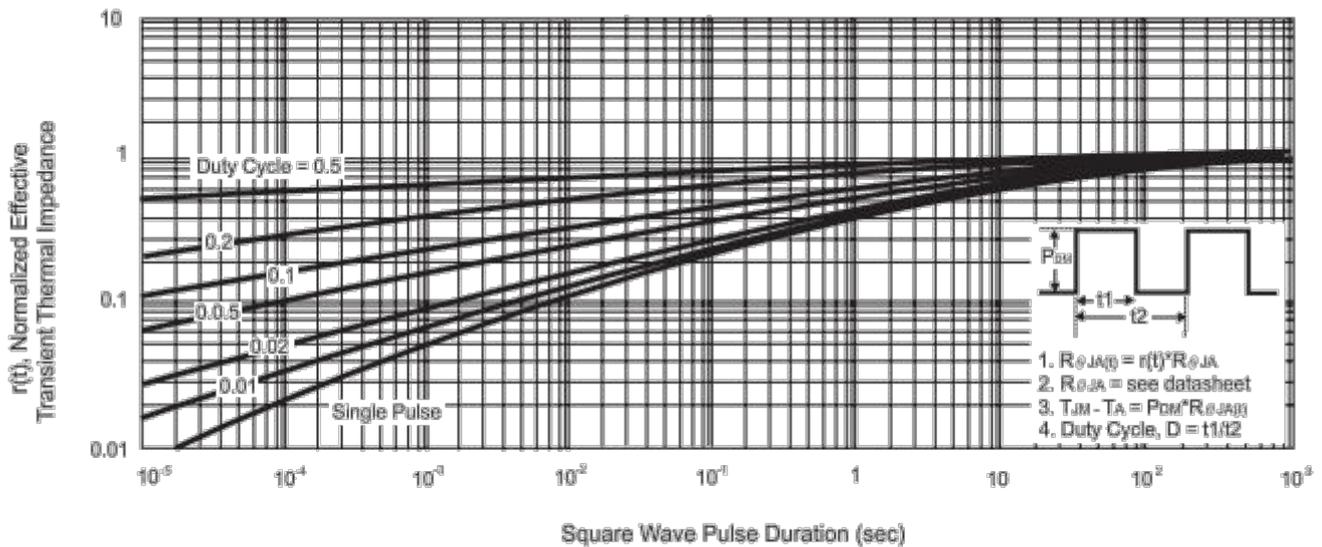


Figure 11. Normalized Thermal Transient Impedance Curve

• Test circuit

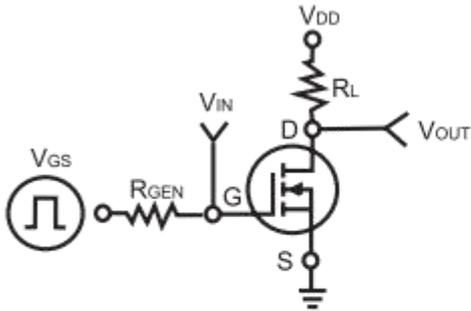


Figure 11. Switching Test Circuit

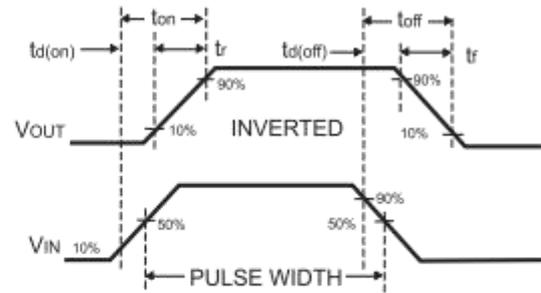
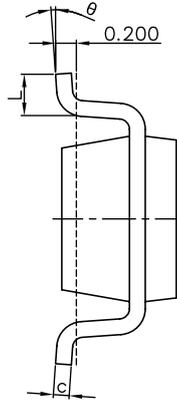
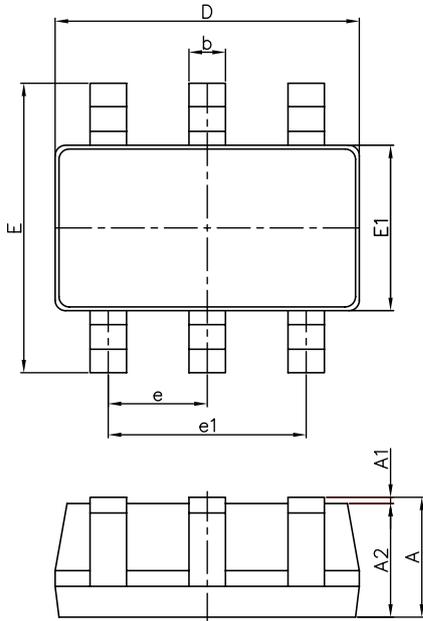
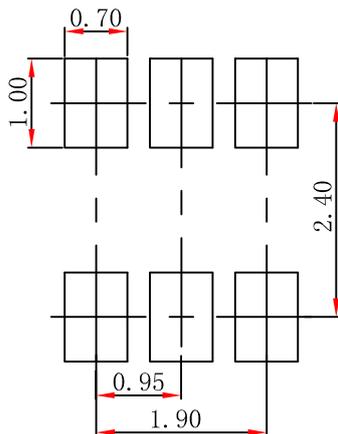


Figure 12. Switching Waveforms

SOT-23-6L Package Outline Dimensions



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 1.050 | 1.250 | 0.041 | 0.049 |
| A1 | 0.000 | 0.100 | 0.000 | 0.004 |
| A2 | 1.050 | 1.150 | 0.041 | 0.045 |
| b | 0.300 | 0.500 | 0.012 | 0.020 |
| c | 0.100 | 0.200 | 0.004 | 0.008 |
| D | 2.820 | 3.020 | 0.111 | 0.119 |
| E1 | 1.500 | 1.700 | 0.059 | 0.067 |
| E | 2.650 | 2.950 | 0.104 | 0.116 |
| e | 0.950(BSC) | | 0.037(BSC) | |
| e1 | 1.800 | 2.000 | 0.071 | 0.079 |
| L | 0.300 | 0.600 | 0.012 | 0.024 |
| θ | 0° | 8° | 0° | 8° |



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.